

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Sheet	1	of	1
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Application Number	not yet assigned
Filing Date 03/02/2004	concurrently herewith
First Named Inventor	Glenn A. Rinne
Group Art Unit 1725	10790967
Examiner Name	
Attorney Docket Number	9180-10CT

Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code (if known)		
AM	1.	US-3,602,979		La lacona, Felix P.	09/00/1971
	2.	US-3,923,231		Catalano et al;	12/00/1975
	3.	US-4,325,734		Burrage et al;	04/00/1982
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	7.	US-5,392,982		Li, Chou H.	02/00/1995
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[illegible]

Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
AM	17.	US 2002/0157247A1 Li (10/31/02)	
AM	18.	US 2002/0074381A1 Rinne et al. (6-20-02).	
AM	19.	E.K. Yung et al; <i>Flip-Chip Process Utilizing Electroplated Solder Joints</i> ; Proceedings of the Technical Conference, 1990 International Electronics Packaging Conference, September 10-12, 1990 pp 1065-1079.	

Thus

10/21/2005

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